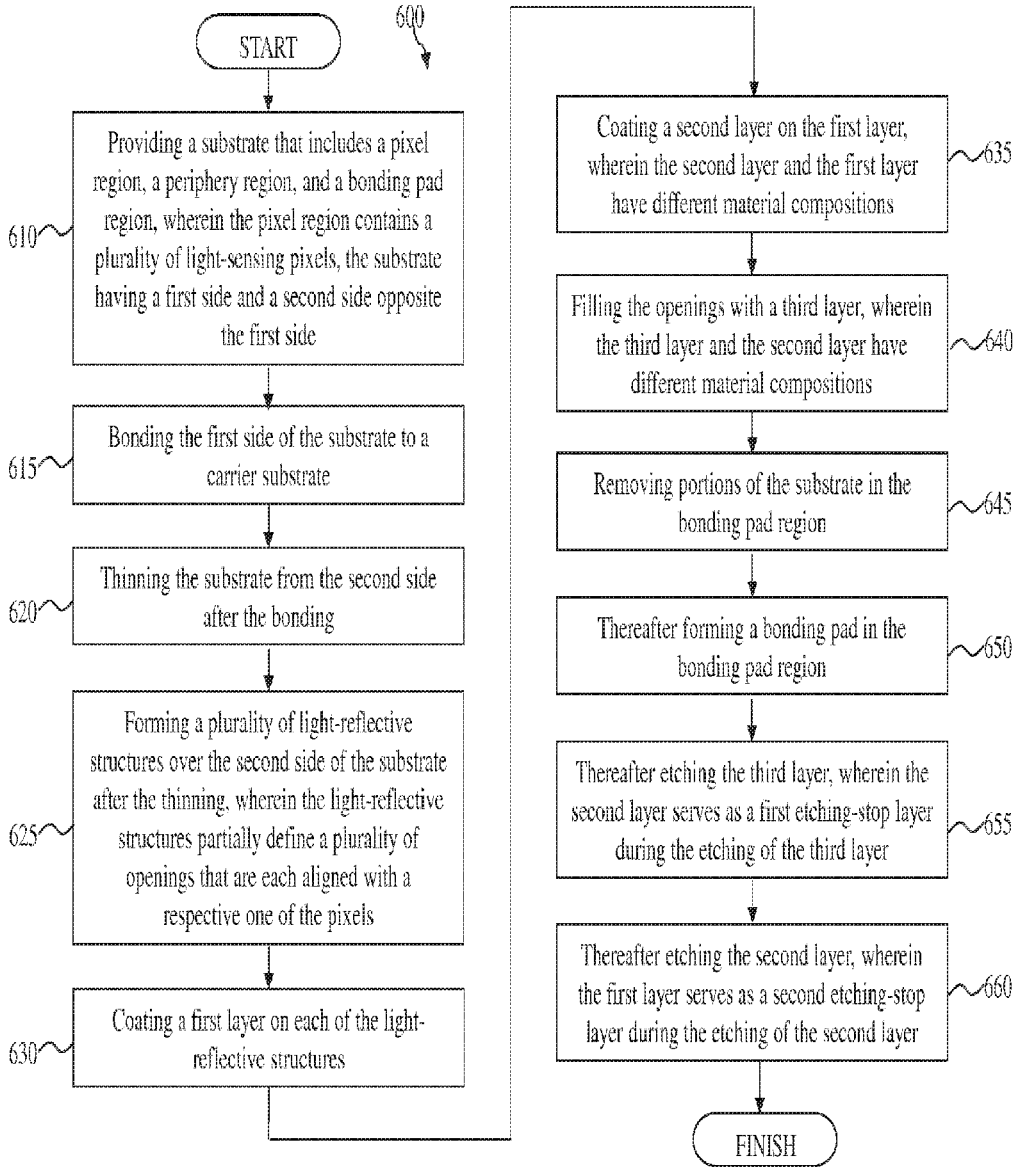
600
START
610
Providing a substrate that includes a pixel region, a periphery region, and a bonding pad region, wherein the pixel region contains a plurality of light-sensing pixels, the substrate having a first side and a second side opposite the first side
615
Bonding the first side of the substrate to a carrier substrate
620
Thinning the substrate from the second side after the bonding
625
Forming a plurality of light-reflective structures over the second side of the substrate after the thinning, wherein the light-reflective structures partially define a plurality of openings that are each aligned with a respective one of the pixels
630
Coating a first layer on each of the light-reflective structures
635
Coating a second layer on the first layer, wherein the second layer and the first layer have different material compositions
640
Filling the openings with a third layer, wherein the third layer and the second layer have different material compositions
645
Removing portions of the substrate in the bonding pad region
650
Thereafter forming a bonding pad in the bonding pad region
655
Thereafter etching the third layer, wherein the second layer serves as a first etching-stop layer during the etching of the third layer
660
Thereafter etching the second layer, wherein the first layer serves as a second etching-stop layer during the etching of the second layer
FINISH

Fig. 28